

TOP LAYER

- COPPER (BOARD PLANE)
- COPPER (BOTTOM)
- SOLDER MASK (BOTTOM)

PLACES WITHIN DATA CLASS

APPROX. NO. CELLS

NAME: LAYER (IF APPLICABLE)

NOTES

CLEARANCE: DIA. HOLES PER ROUTER/GERB PLACES (FOR ROUTING) MUST BE 0.03125 INCHES

0.888	0.888	0.888	0.888
0.888	0.888	0.888	0.888
0.888	0.888	0.888	0.888
0.888	0.888	0.888	0.888

TOP SIDE GROUND PLANE: RELATIVE 0.010 THICK TOLERANCE +/- 0.001 E BEZ 0.010 SPACED AND 0.010 THICK

NO LACING LEGEND

SOLDER MASK: 0.010 THICK, 0.010 CORN

ALL HOLE DIAMETERS ARE AFTER PLATING TOLERANCE

FIN = 4.00E+00 +/- 0.001 E BEZ CORN

1/2 OZ COPPER (WHICH LAYER)

COPPER PLATING IN ALL HOLES TO BE 0.010 MINIMUM

FINISH: MINIMUM OF 0.0010 INCHES OVER 0.0010 INCHES

CRITICAL AREA IS TOP SIDE (ON PLANE) FINISH IS IN 2 AREAS IN CENTER OF BOARD

MASK: IS ELECTROPLATED GOLD/NICKEL

NICKEL PER ASTM B560-02, TYPE CLASS 1

EGD: PER JPCA B560-02, TYPE 1, HARDNESS C, CLASS 0.05

ORIGINAL HOLE LOCATION IS UNLIMITED TO ITS CLEARANCE PAX +/- 0.001

LOCATE ALL PTH HOLES BY PAX, BY PZ OR CENTER

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B/MECL	RTY	DIA	TOL +	TOL -	PLATED	NOTE
4	221	.810	.891	.810	YES	VAS (LACE+88)(RTY=18)
3	22	.150	.001	.001	NO	DIE ALIGNMENT RING
A	B	.170	.001	.001	NO	CLEARANCE
Y	22	.120	.002	.002	YES	DIE MOUNTING (DIA=10)
H	4	.062	.001	.001	NO	SOCKET
3	12	.110	.002	.002	NO	SOCKET
T	4	.056	.002	.002	YES	RING
0		.001	.001	.001		